

UPDATED 08/21/2007

7.10-7.90GHz 4-Watt Internally-Matched Power FET

FEATURES

- 7.10–7.90GHz Bandwidth
- Input/Output Impedance Matched to 50 Ohms
- +36.5 dBm Output Power at 1dB Compression
- 8.5 dB Power Gain at 1dB Compression
- 35% Power Added Efficiency
- -46 dBc IM3 at PO = 25.5 dBm SCL
- 100% Tested for DC, RF, and R_{TH}



EIC7179-4

Caution! ESD sensitive device.

ELECTRIC	AL CHARACTERISTICS ($T_a = 25^{\circ}C$)	Caution! ESD sensitive device.			
SYMBOL	PARAMETERS/TEST CONDITIONS ¹	MIN	TYP	MAX	UNITS
P _{1dB}	Output Power at 1dB Compression f = 7.10-7.90GHz V _{DS} = 10 V, $I_{DSQ} \approx 1100$ mA	35.5	36.5		dBm
G _{1dB}		7.5	8.5		dB
ΔG	Gain Flatness $f = 7.10-7.90GHz$ $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 1100 \text{ mA}$			±0.6	dB
PAE	Power Added Efficiency at 1dB Compression V_{DS} = 10 V, $I_{DSQ} \approx 1100$ mAf = 7.10-7.90GHz		35		%
Id _{1dB}	Drain Current at 1dB Compression f = 7.10-7.90GHz		1200	1400	mA
IM3	Output 3rd Order Intermodulation Distortion Δf = 10 MHz 2-Tone Test; Pout = 25.5 dBm S.C.L ² V_{DS} = 10 V, $I_{DSQ} \approx 65\%$ IDSSf = 7.90GHz	-43	-46		dBc
I _{DSS}	Saturated Drain Current V_{DS} = 3 V, V_{GS} = 0 V		2000	2500	mA
V _P	Pinch-off Voltage V_{DS} = 3 V, I_{DS} = 20 mA		-2.5	-4.0	V
R _{TH}	Thermal Resistance ³		5.5	6.0	°C/W

Note: 1. Tested with 100 Ohm gate resistor.

2. S.C.L. = Single Carrier Level.

3. Overall Rth depends on case mounting.

ABSOLUTE MAXIMUM RATING FOR EFE

SYMBOLS	PARAMETERS	ABSOLUTE ¹	CONTINUOUS ²	
Vds	Drain-Source Voltage	15V	10V	
Vgs	Gate-Source Voltage	-5V	-4V	
Igf Forward Gate Current		48mA	14.4mA	
lgr	Reverse Gate Current	-9.6mA	-2.4mA	
Pin	Input Power	36dBm	@ 3dB Compression	
Tch	Channel Temperature	175C	175C	
Tstg	Tstg Storage Temperature		-65C to +175C	
Pt	Total Power Dissipation	25W	25W	

Note: 1. Exceeding any of the above ratings may result in permanent damage.

2. Exceeding any of the above ratings may reduce MTTF below design goals.



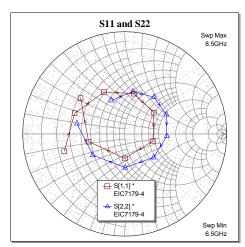
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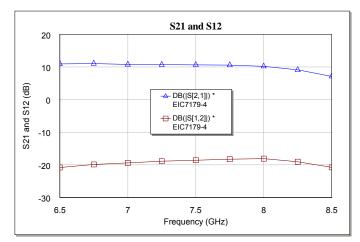
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PERFORMANCE DATA

Typical S-Parameters (T= 25°C, 50 Ω system, de-embedded to edge of package) V_{DS} = 10 V, I_{DSQ} ≈ 1100mA





FREQ	S11		S21		S12		S22	
(GHz)	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
6.25	0.717	-129.010	3.341	8.410	0.078	-50.550	0.258	158.370
6.50	0.616	-164.030	3.517	-25.170	0.091	-84.550	0.352	111.870
6.75	0.531	157.650	3.563	-58.820	0.101	-117.910	0.422	78.950
7.00	0.458	116.510	3.454	-90.850	0.107	-148.130	0.460	51.440
7.25	0.405	77.140	3.425	-121.930	0.114	-179.030	0.451	25.010
7.50	0.354	36.120	3.404	-154.300	0.118	149.090	0.413	-2.990
7.75	0.285	-14.050	3.372	171.750	0.122	117.150	0.365	-39.080
8.00	0.240	-89.650	3.238	134.430	0.125	81.280	0.329	-89.170
8.25	0.362	-167.970	2.854	95.090	0.111	42.800	0.375	-146.450
8.50	0.557	140.990	2.268	56.400	0.091	6.000	0.480	167.620
8.75	0.698	106.670	1.652	22.050	0.068	-26.910	0.568	137.060

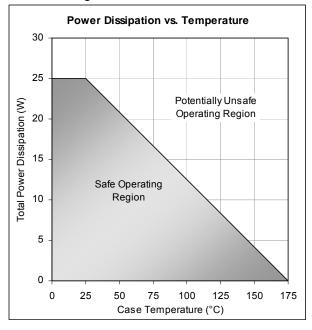


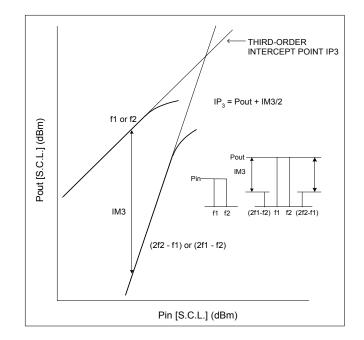
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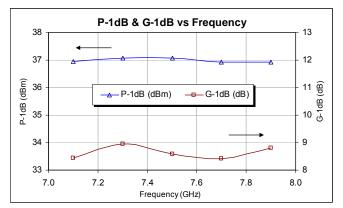
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Power De-rating Curve and IM3 Definition

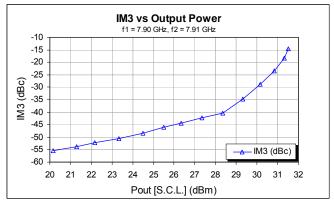




Typical Power Data (V_{DS} = 10 V, I_{DSQ} = 1100 mA)



Typical IM3 Data (V_{DS} = 10 V, $I_{DSQ} \approx 65\%$ IDSS)





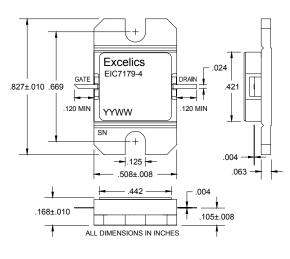
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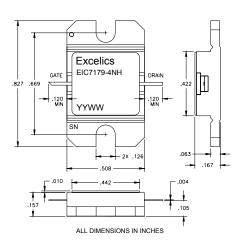
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PACKAGES OUTLINE Dimensions in inches, Tolerance + .005 unless otherwise specified

EIC7179-4 (Hermetic)



EIC7179-4NH (Non-Hermetic)





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ORDERING INFORMATION

Part Number	Packages	Grade ¹	f _{Test} (GHz)	P _{1dB} (min)	IM_3 (min) ²
EIC7179-4	Hermetic	Industrial	7.10-7.90GHz	35.5	-43
EIC7179-4NH	Non-Hermetic	Industrial	7.10-7.90GHz	35.5	-43

Notes: 1. Contact factory for military and hi-rel grades.

2. Exact test conditions are specified in "Electrical Characteristics" table.

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